

# N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V} \,$

## **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

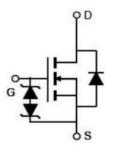
#### **Features**

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V <sub>DS min@Tjmax</sub>	710	V
R <sub>DS(ON)TYP</sub> .	260	mΩ
$I_D$	13	Α
Qg	15	nC



Schematic diagram

## **Package Marking And Ordering Information**

Device	Device Package	Marking
NCE65N290D	TO-263	NCE65N290D



TO-263-2L

V1.0

Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (Vgs=0V)	V <sub>DS</sub>	650	V
Gate-Source Voltage (VDS=0V) ,AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) ,DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	13	А
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	9.1	А
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	39	Α
Maximum Power Dissipation(Tc=25℃)	P <sub>D</sub>	127	W
Derate above 25°C		0.85	W/°C
Single pulse avalanche current (Note 2)	I <sub>AS</sub>	3	Α
Reverse diode dv/dt, V <sub>DS</sub> ≤480 V,I <sub>SD</sub> <i<sub>D</i<sub>	dv/dt	15	V/ns
Drain Source voltage slope,V <sub>DS</sub> ≤480 V	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55+175	°C



### **Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance,Junction-to-Case(Maximum)	R <sub>thJC</sub>	1.18	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250uA	650			V
Zero Gate Voltage Drain Current(Tc=25°ℂ)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			50	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±200	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250uA	3	3.5	4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =6.5A		260	290	mΩ
Dynamic Characteristics						
Gate Resistance	Rg	F=1MHZ, D-S short		16		Ω
Input Capacitance	C <sub>lss</sub>	\/ -50\/\/ -0\/		847		pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V,		37		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1MHz		5		pF
Total Gate Charge	Qg			15	18	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =450 $V$ , $I_{D}$ =6.5 $A$ ,		2		nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V		5		nC
Gate plateau voltage	Vgp			5.3		V
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>			10		nS
Turn-on Rise Time	tr	$V_{DD}$ =380 $V$ , $I_{D}$ =6.5 $A$ ,		9		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G$ =4 $\Omega$ , $V_{GS}$ =10 $V$		55		nS
Turn-Off Fall Time	t <sub>f</sub>			9		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T 05°0			13	Α
Pulsed-Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			39	Α
Forward on voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =13A,V <sub>GS</sub> =0V		0.9	1.1	V
Reverse Recovery Time	t <sub>rr</sub>			230		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I <sub>F=</sub> 6.5A,		1.84		uC
Peak reverse recovery current	I <sub>rrm</sub>	di/dt=100A/µs		16		Α

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25  $^{\circ}\text{C}$  ,VDD=50V,VG=10V, RG=25 $\Omega$ 



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

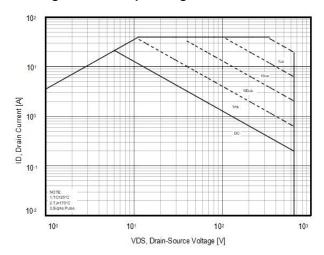


Figure 2. Source-Drain Diode Forward Voltage

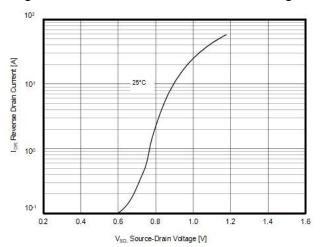


Figure 3. Transfer characteristics

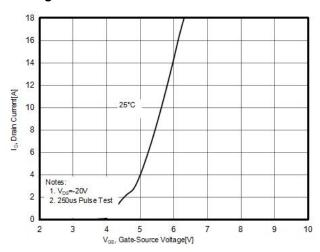


Figure 4. Output characteristics

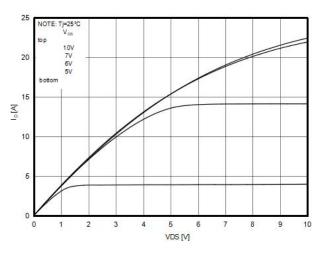


Figure 5. Static drain-source on resistance

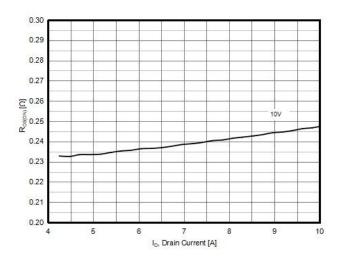
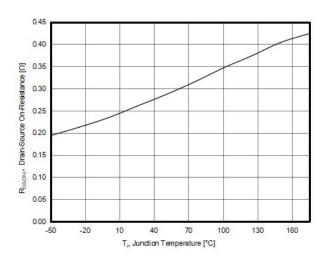


Figure 6. RDS(ON) vs Junction Temperature



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Figure 7. BV<sub>DSS</sub> vs Junction Temperature

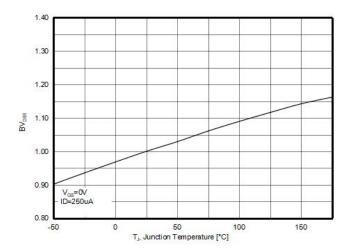


Figure 8. Maximum  $I_{\mbox{\scriptsize D}}$  vs Junction Temperature

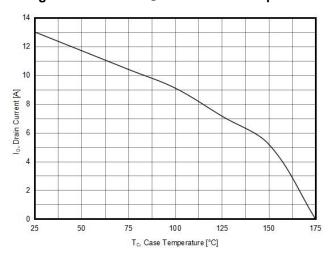


Figure 9. Gate charge waveforms

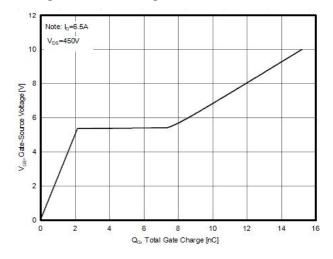
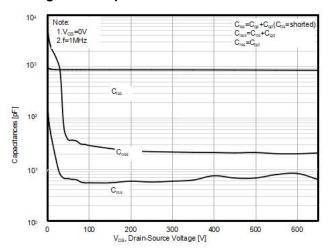


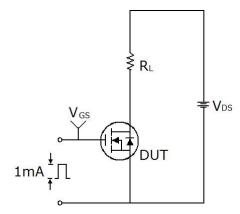
Figure 10. Capacitance

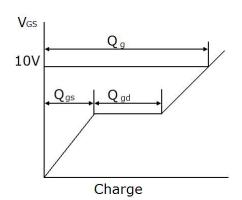




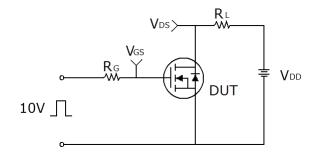
## **Test circuit**

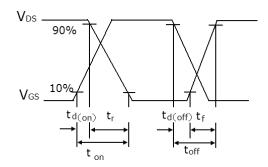
## 1) Gate charge test circuit & Waveform



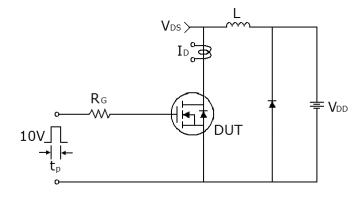


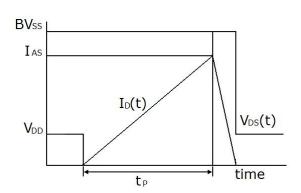
## 2) Switch Time Test Circuit:





## 3) Unclamped Inductive Switching Test Circuit & Waveforms

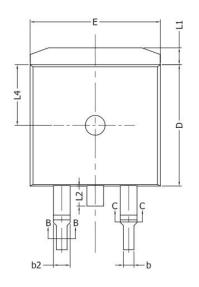


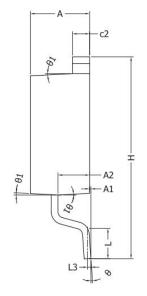


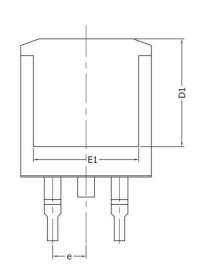
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# **TO-263-P Package Information**







Symbol	Dimensions	In Millimeters	Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
А	4.40	4.60	0.173	0.181		
A1	0.00	0.25	0.000	0.010		
A2	2.20	2.60	0.087	0.102		
b	0.76	0.89	0.030	0.035		
b1	0.75	0.85	0.030	0.033		
b2	1.23	1.37	0.048	0.054		
b3	1.22	1.32	0.048	0.052		
С	0.47	0.60	0.019	0.024		
c1	0.46	0.56	0.018	0.022		
c2	1.25	1.35	0.049	0.053		
D	9.10	9.30	0.358	0.366		
D1	8.00		0.315			
Е	9.80	10.00	0.386	0.394		
E1	7.80		0.307			
е	2.54	2.54BSC		DBSC		
Н	14.90	15.70	0.587	0.618		
L	2.00	2.60	0.079	0.102		
L1	1.17	1.40	0.046	0.055		
L2		1.75		0.069		
L3	0.25	BSC	0.101BSC			
L4	4.60	4.60REF		0.181REF		



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